CLAIMS

[Claim 1]

An electrically conductive adhesive composition comprising an organic acid (A), an electrically conductive filler (B) and a binder resin (C1), wherein

the electrically conductive adhesive composition contains from 0.01 to 0.15 mass% of the organic acid (A) and 85 mass% or more of the electrically conductive filler (B), relative to the overall amount of the electrically conductive adhesive composition,

the organic acid (A) has an acid dissociation constant pKa of 4.8 or less,

the electrically conductive adhesive composition may further contain at least one selected from the group consisting of a diluent (C2), a curing agent (C3), and a curing accelerator (C4), and

denoting [B] mass% as the content of the electrically conductive filler (B) and denoting [C] mass% as the sum of the contents of the binder resin (C1), the diluent (C2), the curing agent (C3) and the curing accelerator (C4), [B]/[C] is 95/5 or more.

[Claim 2]

An electrically conductive adhesive composition comprising an organic acid (A), an electrically conductive filler (B) and a binder resin (C1), wherein

the electrically conductive adhesive composition contains from 0.01 to 0.2 mass% of the organic acid (A) and from 85 to 93 mass% of the electrically conductive filler (B), relative to the overall amount of the electrically conductive adhesive composition,

the organic acid (A) has an acid dissociation constant pKa of 4.8 or less,

the electrically conductive adhesive composition may further contain at least one selected from the group consisting of a diluent (C2), a curing agent (C3), and a curing accelerator (C4), and

denoting [B] mass% as the content of the electrically conductive filler (B) and denoting [C] mass% as the sum of the contents of the binder resin (C1), the diluent (C2), the curing agent (C3) and the curing accelerator (C4), [B]/[C] is 95/5 or more.

[Claim 3]

The electrically conductive adhesive composition according to claim 1 or 2, wherein the organic acid (A) has a molecular weight of 170 or more.

[Claim 4]

The electrically conductive adhesive composition according to any one of claims 1 to 3, wherein the organic acid (A) is at least one organic acid selected from the group consisting of abietic acid, pimaric acid, isopimaric acid, palustric acid, dehydroabietic acid, neoabietic acid, sebacic acid, ascorbic acid, and suberic acid.

[Claim 5]

A cured electrically conductive adhesive obtained by curing the electrically conductive adhesive composition according to any one of claims 1 to 4.

[Claim 6]

An electronic device in which the electrically conductive adhesive composition according to any one of claims 1 to 4 is used for the adhesion of a component.